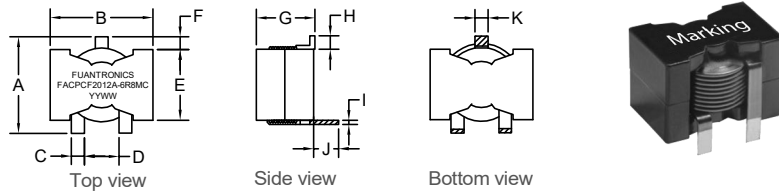


P/N: FACPCF2012A-6R8MC



Outline Dimensions(Unit:mm)

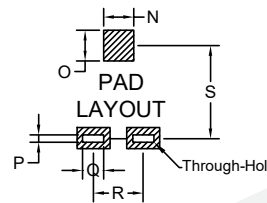


A	B	C	D	E	F	G	H	I	J	K
Max	Max	±0.30	±0.60	Max	±0.30	Max	±0.30	±0.20	±1.00	±0.20
21.0	21.8	2.50	7.00	14.5	2.50	12.0	2.00	0.70	5.00	2.50

Electronical Schematic



Suggested Pad layout



N	5.00 REF
O	5.00 REF
P	1.20 REF
Q	3.50 REF
R	9.50 REF
S	17.5 REF

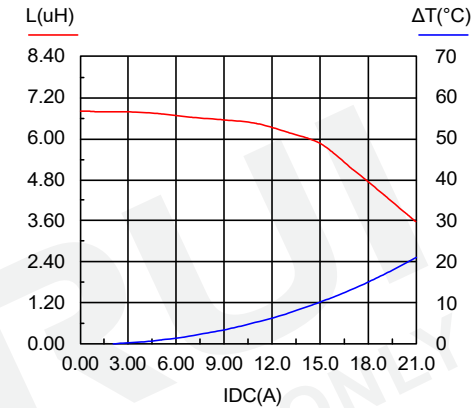
- \*\*\*Assemblage design, sturdy structure.
- \*\*\*High inductance, high current, low magnetic loss, low ESR, small parasitic capacitance.
- \*\*\*Flat wire winding, achieve a low D.C. Resistance.
- \*\*\*Temperature rise current and saturation current is less influenced by environment.

Electrical Characteristics(@25°C)

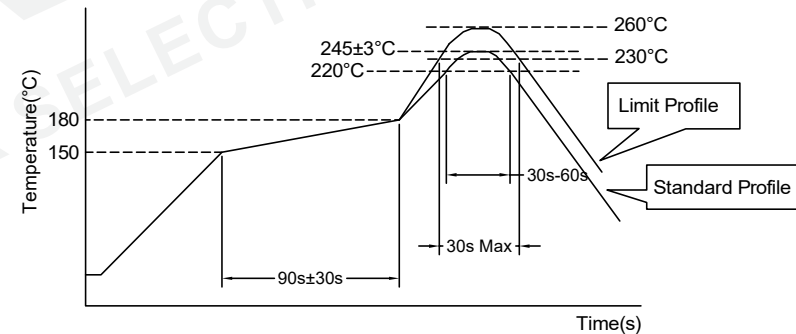
Inductance 100KHz,0.1V	DC Resistor	Saturated current 16.0A	Temperature rise current 28A
6.80uH±20%	2.40mΩ Max	L(16.0A)=80%*L0A Typ	T≤40°C Typ

- \*\*\*Saturation current: the actual value of DC current when the inductance decrease 20% of its initial value.
- \*\*\*Temperature rise current: the actual value of DC current when the temperature rise is ΔT40°C(Ta=25°C).
- \*\*\*Operating Temperature: -40°C~+125°C (Temperature rise included)
- \*\*\*Storage Temperature: -40°C~+125°C
- \*\*\*Storage Humidity:RH10%~70%.

Saturation current VS temperature rise current curve:



Recommended Soldering Temperature Graph.



	Standard Profile	Standard Profile
Pre-heating	150~180°C,90s±30s	
Heating	above 220°C,30s-60s	above 240°C,30s Max
Peak temperature	245°C±3°C	260°C,10s
Cycle of reflow	2 times	2 times